

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

Claims 1-16 (Cancelled)

17. (New) A microwave package, the walls of which delimiting an internal cavity to accommodate a microwave device, said package comprising:

a upper wall,

a lower wall constituting the base of said package, intended to be mounted on an exterior circuit board comprising connection points to connect electrically said microwave device with said exterior circuit, some of the connection points being connected with some inputs/outputs of said microwave device and some other connection points being connected with the package earth;

side walls between the upper face and the lower face;

wherein, the external faces of the walls being conductive, said package forms a Faraday cage around the cavity; the inputs/outputs of the microwave device being linked to the corresponding connection points of the base by means of metallized holes passing through the package base; each metallized hole being linked by one end, via a conductive link situated in the cavity, to an input or an output of the microwave device, and by the other end, passing through the base of the package, to the corresponding connection point situated on the external face of the package base; a metallized hole conveying a signal being surrounded by other metallized holes linked to the earth so as to form a coaxial connection.

18. (New) The package according to claim 17, wherein a connection point is linked to an input-output by a metallized hole forming a straight connection, said connection being perpendicular to the exterior circuit on which the package is mounted.

19. (New) The package according to claim 17, wherein the base being formed by an insulating material partially covered with a conductive layer, the metallized holes conveying microwave signals pass through the insulating material.

20. (New) The package according to claim 17, wherein each connection point situated on the external face of the package base comprises a conducting earth or signal ball.

21 (New) The package according to claim 20, further comprising a coaxial structure formed by some conducting balls linked to the Faraday cage and forming earth connection points placed around each conducting ball forming a signal connection point, said coaxial structure making a shielding of said signal connection.

22. (New) The package according to claim 21, wherein earth conducting balls placed around a signal conducting ball are at least three in number.

23. (New) The package according to claim 22, wherein earth conducting balls are distributed around a signal conducting ball over 360°.

24. (New) A mounting comprising a package as claimed in claim 17 and a multilayer circuit comprising a first conducting earth plane on its surface and connection points with metallized holes passing through the circuit to link said connection points to some tracks inside the circuit so as to convey signals across the earth plane to said tracks, said connection points being arranged so as to be opposite the signal connection points of the package when the package is mounted on the multilayer circuit.

25. (New) The mounting according to claim 24, wherein the multilayer circuit comprises a second conducting earth plane on the side opposite the side of the first earth plane, the two earth planes being on either side of the tracks.

26 (New) The mounting according to claim 25, wherein the conducting earth planes of the multilayer circuit are linked together by metallized holes.

27 (New) The mounting according to claim 25, wherein the earth conducting balls of the package are linked to at least one conducting earth plane of the multilayer circuit.

28 (New) The package according to claim 17, wherein the microwave device is placed in the internal cavity on the internal face of the lower wall.

29. (New) A microwave component package, comprising:

 a lower wall defining the base of said package, configured to be mounted on an exterior circuit board, the base having an interior layer with connection points and an exterior layer with connection points;

 side metal walls disposed on the lower wall to form an interior volume;

 a top metal plate disposed on the side walls, thereby forming a Faraday cage around the interior volume; and

 a microwave component disposed inside the Faraday cage, said microwave component having inputs/outputs electrically connected to the connection points of the interior layer;

 wherein said base has a plurality of singal metallized holes passing therethrough for conveying a microwave signal between the microwave component and the exterior circuit board, and a plurality of earth metallized holes passing therethrough for surrounding each of the singal metallized holes so as to form a coaxial structure.

30 (New) The package as claimed in claim 29, wherein said metallized holes form straight connections between the connection points of the interior layer and exterior layer and said connections are perpendicular to the exterior circuit on which the package is mounted.

31 (New) The package as claimed in claim 29, wherein the base is formed by an insulating material formed and is partially covered with a conductive layer, and the metallized holes conveying microwave signals pass through the insulating material.

32 (New): The package according to claim 29, wherein each connection point on the external layer of the base comprises a conducting earth or signal ball.

33 (New) The package as claimed in claim 29, wherein the coaxial structure has signal ball and a plurality of conducting earth balls connected electrically to the Faraday cage and placed around the signal ball.

34 (New) The package as claimed in claim 29, wherein the earth metallized holes surrounded around the signal metallized hole are at least three in number.

35. (New) The package as claimed in claim 29, wherein the earth metallized holes surrounded around the signal metallized hole are distributed around the signal ball over 360°.